

Full Material Declaration for attached parts list

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Declarations authorised by:

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Declaration effective from: 06 December 2016 [Approved on 25 July 2025, 19:46 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.43128%	TITANIUM	7440-32-6	0.1%
			Elemental nickel REACH Article 67 Exemption	7440-02-0	0.6%
			SILVER, ELEMENTAL	7440-22-4	2.4%
			Silicon	7440-21-3	96.9%
Die attach	Lead and Lead alloys	0.99526%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead Exempt from other regulatory requirements EU RoHS Exemption 27 Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	18.4834%	Carbon black	1333-86-4	0.4%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	1%
			TBBA-epichlorhydrin oligomer Exempt from other regulatory requirements	40039-93-8	1%
			Phenol, polymer with formaldehyde	9003-35-4	6.5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	13%
			Quartz sand	60676-86-0	15%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Leadfinish Leadframe	Tin plating Copper (e.g. copper amounts in cable harnesses)	1.56398% 78.5261%	Crystalline silica Exempt from other regulatory requirements	14808-60-7	63.1%
			Tin	7440-31-5	100%
			Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
A-405	Diode axial	0.211	g